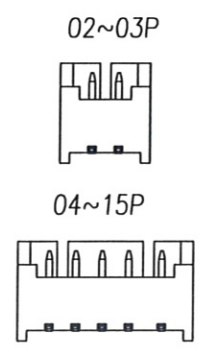
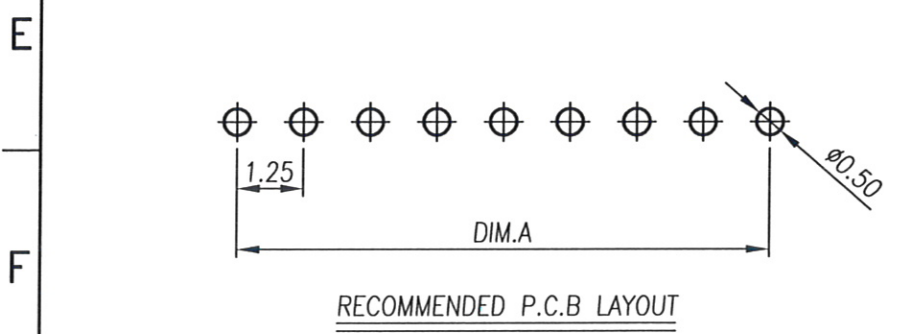
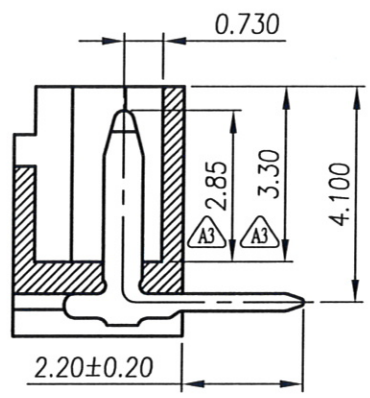
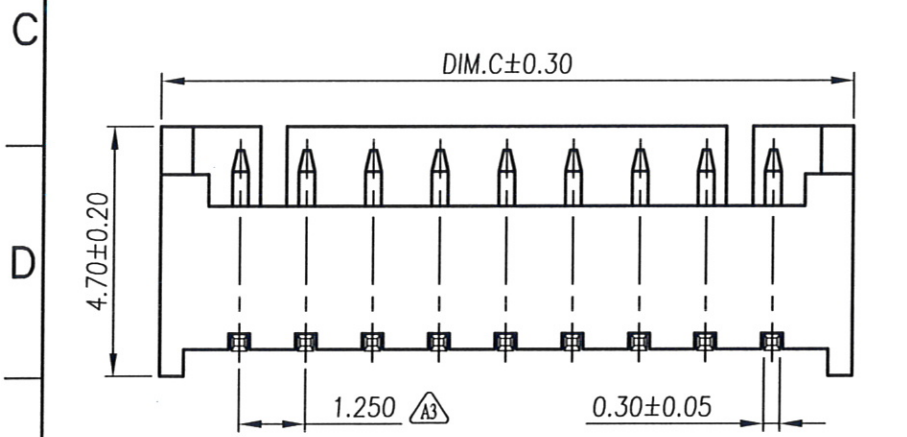


PIN	DIM.A	DIM.B	DIM.C
02	1.25	3.05	4.25
03	2.50	4.30	5.50
04	3.75	5.55	6.75
05	5.00	6.80	8.00
06	6.25	8.05	9.25
07	7.50	9.30	10.50
08	8.75	10.55	11.75
09	10.00	11.80	13.00
10	11.25	13.05	14.25
11	12.50	14.30	15.50
12	13.75	15.55	16.75
13	15.00	16.80	18.00
14	16.25	18.05	19.25
15	17.50	19.30	20.50




REV	MODIFICATION	DATE	DRAW
A1	Release To ECN20111110	2011.11.29	Ivy
A2	Release To ECN20130306	2013.03.14	Seven
A3	Release To ECN20150702	2015.07.13	Michelle

RoHS Compliant

- Specification
- 1.Current Rating:1A AC/DC
 - 2.Voltage Rating:125V AC
 - 3.Contact Resistance:20mΩ Max.(Initial) 40mΩ Max.(Final)
 - 4.Insulation Resistance:100MΩ Min. At DC500V
 - 5.Dielectric Withstanding Voltage:AC250V/Minute
 - 6.Operating Temperature:-25°C~+85°C


- Material:
- 1.Housing:High Temperature Thermoplastic UL94V-0
 - 2.Contact Pin:Copper Alloy T=0.30mm
- Finish:
- 1.Housing:See P/N Option
 - 2.Contact Pin:See P/N Option
- Part No.: AD07601 XX X X 7 1
- No. Of Pin: 02~15
- Packing: 7:Box
- Housing Material: _____
- 3:Ny46 UL94V-0 Natural
- K:HTN UL94V-0 Natural H.F
- V:Ny46 UL94V-0 Natural Dye Red
- Plating:
- 1:Bright Tin Plated Over Ni
 - 2:Matte Tin Plated Over Ni
 - 3:Gold Flash Over Ni



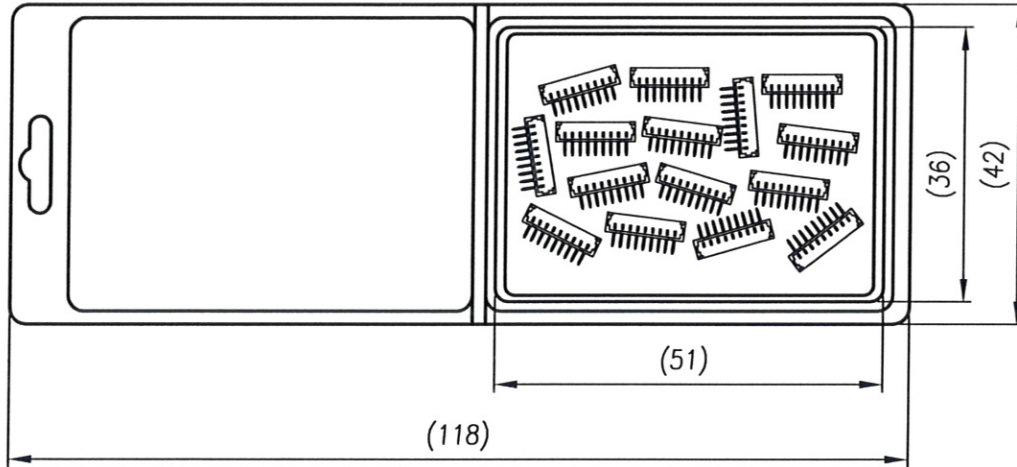
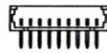


金上達科技股份有限公司

GOLDENSUNDA TECHNOLOGY CO.,LTD

TOLERANCE UNLESS OTHERWISE SPECIFIED		PROJ. 	TITLE: Wire To Board Wafer 1.25mm 90° DIP Single Row	
.x± 0.35	x.'± 2'	APR. C.F.Liao 20150713	PART NO. AD07601XXXX71	DWG NO. AD07601XXXX71
.xx± 0.25	.x'± 1'	CHK: Abel 20150713	UNITS: mm	CUSTOMER DRAWING
.xxx± 0.15	.xx'± 0.5'	DRA: Michelle 20150713	SIZE: A4	SCALE 7:1
		SHEET 1 / 2	REV A3	

RoHS Compliant

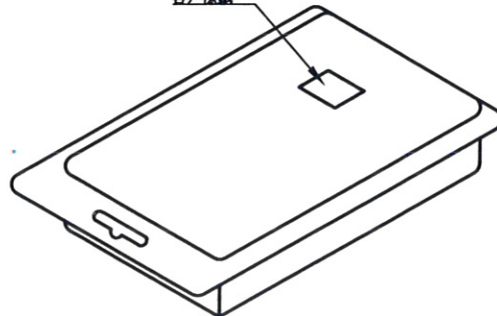


每盒包裝數量,參考下列:

PIN數	數量
02 ~ 04	1000
05 ~ 06	600
07 ~ 08	500
09 ~ 10	400
11 ~ 12	300
13 ~ 15	200



客戶標籤



REV	MODIFICATION	DATE	DRAW
A1	Release To ECN20111110	2011.11.29	Ivy
A2	Release To ECN20130306	2013.03.14	Seven
A3	Release To ECN20150702	2015.07.13	Michelle



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GOLDENSUNDA TECHNOLOGY CO.,LTD

TOLERANCE UNLESS OTHERWISE SPECIFIED		PROJ.	TITLE: Wire To Board Wafer 1.25mm 90° DIP Single Row	
.x± 0.35	x:± 2'	APR. C.F.Liao 20150713	PART NO. AD07600XXXX71	DWG NO. AD07601XXXX71
.xx± 0.25	.x:± 1'	CHK. Abel 20150713	UNITS: mm	CUSTOMER DRAWING
.xxx± 0.15	.xx:± 0.5'	DRA. Michelle 20150713	SIZE: A4	SCALE Free
		SHEET 2 / 2		REV A3